

## STR1P2UH7

# P-channel 20 V, 0.087 Ω typ., 1.4 A STripFET™ H7 Power MOSFET in a SOT-23 package

Datasheet - production data

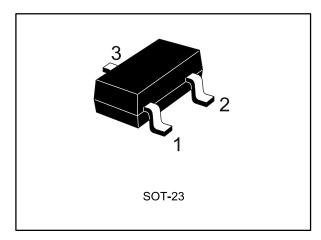
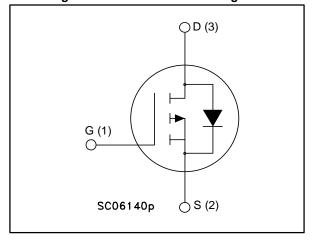


Figure 1: Internal schematic diagram



#### **Features**

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max	l <sub>D</sub>
STR1P2UH7	20 V	0.1 Ω @ 4.5	1.4 A

- Very low on-resistance
- Very low capacitance and gate charge
- High avalanche ruggedness

### **Applications**

Switching applications

### **Description**

This P-channel Power MOSFET utilizes the STripFET H7 technology with a trench gate structure combined with extremely low onresistance. The device also offers ultra-low capacitances for higher switching frequency operations.

**Table 1: Device summary** 

Order code	Marking	Package	Packaging	
STR1P2UH7	1L2U	SOT-23	Tape and reel	



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STR1P2UH7 Electrical ratings

# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage	20	V
$V_{GS}$	Gate-source voltage	±8	V
ID	Drain current (continuous) at T <sub>pcb</sub> = 25 °C	1.4	Α
I <sub>D</sub>	Drain current (continuous) at T <sub>pcb</sub> = 100 °C	0.9	Α
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	5.6	Α
Ртот	Total dissipation at T <sub>pcb</sub> = 25 °C	0.35	W
T <sub>stg</sub>	Storage temperature	- 55 to 150	°C
Tj	Max. operating junction temperature	150	°C

#### Notes:

Table 3: Thermal data

Symbol	Parameter		Unit
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb max, single operation		°C/W

#### Notes:

 $^{(1)}$ When mounted on 1inch² FR-4 board, 2 oz Cu



<sup>&</sup>lt;sup>(1)</sup>Pulse width limited by safe operating area

Electrical characteristics STR1P2UH7

### 2 Electrical characteristics

(T<sub>C</sub> = 25 °C unless otherwise specified)

Table 4: On /off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	20			V
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0			1	μΑ
I <sub>GSS</sub>	Gate-body leakage current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$			10	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	0.4		1	V
		$V_{GS} = 4.5 \text{ V}, I_D = 0.7 \text{ A}$		0.087	0.1	Ω
R <sub>DS(on)</sub>	Static drain-source on-resistance	$V_{GS} = 2.5 \text{ V}, I_{D} = 0.7 \text{ A}$		0.11	0.13	Ω
		$V_{GS} = 1.8 \text{ V}, I_{D} = 0.7 \text{ A}$		0.145	0.18	Ω

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		ı	510	ı	pF
Coss	Output capacitance	$V_{DS} = 10 \text{ V, } f = 1 \text{ MHz,}$		66	-	pF
Crss	Reverse transfer capacitance	V <sub>G</sub> S = 0		44	-	pF
Qg	Total gate charge	$V_{DD} = 10 \text{ V}, I_D = 3 \text{ A},$	ı	4.8	1	nC
$Q_{gs}$	Gate-source charge	$V_{GS} = 4.5 \text{ V}$	ı	0.7	ı	nC
$Q_{gd}$	Gate-drain charge	(see Figure 14: "Gate charge test circuit")	-	0.8	-	nC

**Table 6: Switching times** 

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 1.5 A,	-	9	-	ns
tr	Rise time	$R_G = 4.7 \Omega, V_{GS} = 4.5 V$	ı	21	ı	ns
t <sub>d(off)</sub>	Turn-off delay time	(see Figure 15: "Test circuit for inductive load switching and diode recovery times")	- 1	40	ı	ns
t <sub>f</sub>	Fall time		ı	19	ı	ns



Table 7: Source drain diode

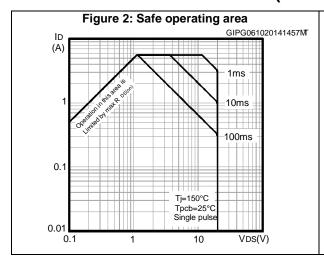
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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub> <sup>(1)</sup>	Forward on voltage	I <sub>SD</sub> = 1 A, V <sub>GS</sub> = 0	ı	ı	1	V
t <sub>rr</sub>	Reverse recovery time	V <sub>DD</sub> = 10 V	ı	12.5		ns
Qrr	Reverse recovery charge	$di/dt = 100 \text{ A/}\mu\text{s}, I_{SD} = 1 \text{ A}$	-	5		nC
IRRM	Reverse recovery current	T <sub>j</sub> = 150 °C (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	0.8		А

#### Notes:

 $<sup>^{(1)}</sup>$ Pulsed: pulse duration = 300  $\mu$ s, duty cycle 1.5%.



## 2.1 Electrical characteristics (curves)



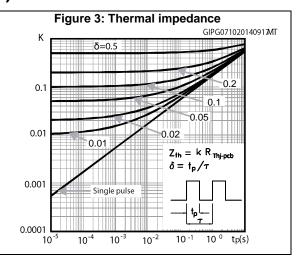


Figure 4: Output characteristics
GIPG300920141410MT

VGS=5, 4.5, 4, 3.5, 3, 2.5V

2V

6

5

4

3

2

1.5V

0

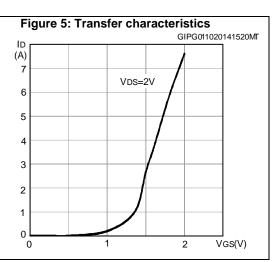
0

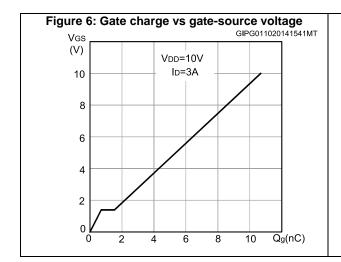
0.5

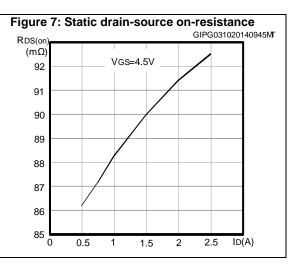
1

1.5

VDS(V)







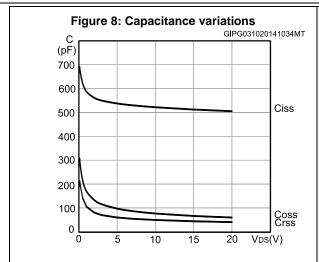
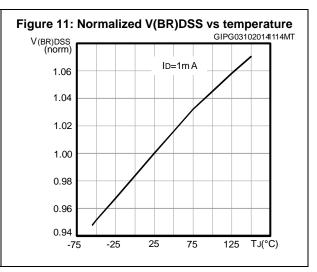
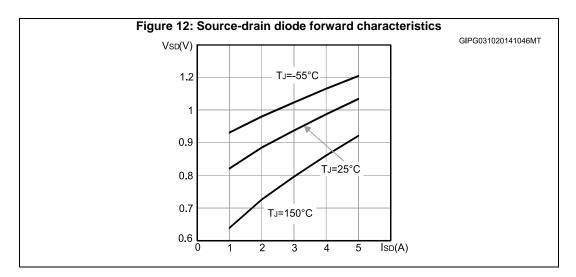


Figure 9: Normalized gate threshold voltage vs temperature GIPG031020141057MT VGS(th) (norm) 1.30 ID=250μA 1.20 1.10 1.00 0.90 0.80 0.70 0.60 0.50 0.40 L 75 25 75 TJ(°C) -25 125





Test circuits STR1P2UH7

### 3 Test circuits

Figure 13: Switching times test circuit for resistive load

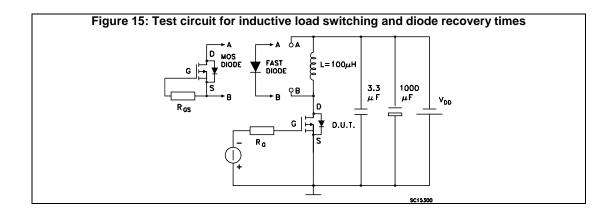
Figure 14: Gate charge test circuit

Figure 14: Gate charge test circuit

Figure 14: Gate charge test circuit

Scis280

Figure 14: Gate charge test circuit



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

### 4.1 SOT-23 package mechanical data

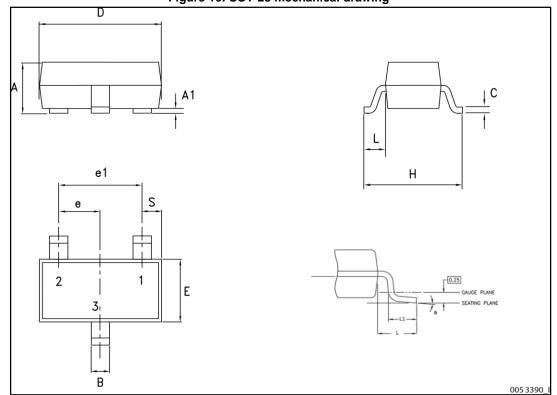
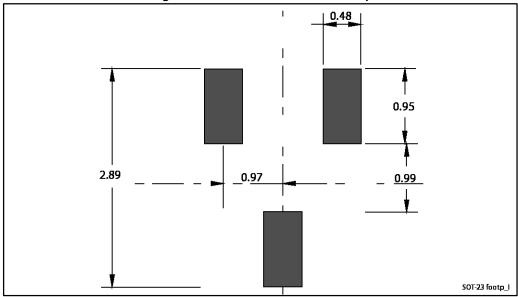


Figure 16: SOT-23 mechanical drawing

Table 8: SOT-23 mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
A	0.89		1.40
A1	0		0.10
В	0.30		0.51
С	0.085		0.18
D	2.75		3.04
е	0.85		1.05
e1	1.70		2.10
E	1.20		1.75
Н	2.10		3.00
L		0.60	
S	0.35		0.65
L1	0.25		0.55
а	0°		8°

Figure 17: SOT-23 recommended footprint





Dimensions are in mm.

STR1P2UH7 Revision history

# 5 Revision history

Table 9: Document revision history

Date	Revision	Changes
18-Jul-2013	1	First release.
07-Oct-2014	2	Document status promoted from target data to preliminary data. Updated title, features and description in cover page. Updated Section 2: "Electrical characteristics". Minor text changes.
05-Jun-2015	3	Document status promoted from preliminary to production data.

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